

REV.	SPECIFICATION	ECN NO.	APPD.
R1		ECN220334	

Material and Plating:

Housing: LCP, UL94V-0, Black.

Signal Contacts :High Performance Copper Alloy.
Gold Plated on Contact Area and 80u" Min Tin Plated on Solder Tail over nickel 50u" Min .

Electrical Characteristics:

Current Rating: 1.5A .

Voltage Rating: 125V AC .

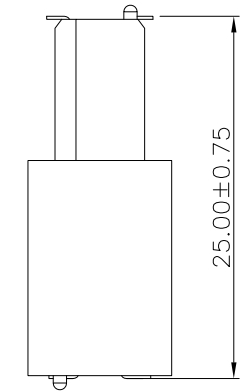
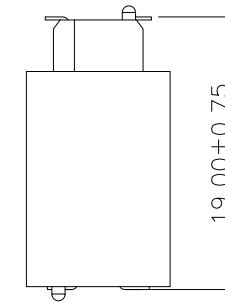
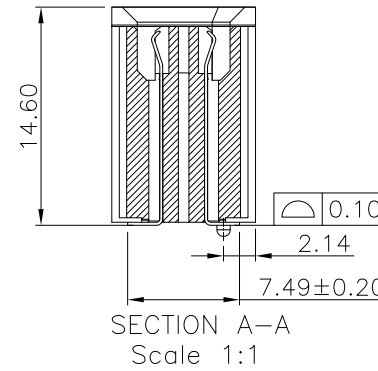
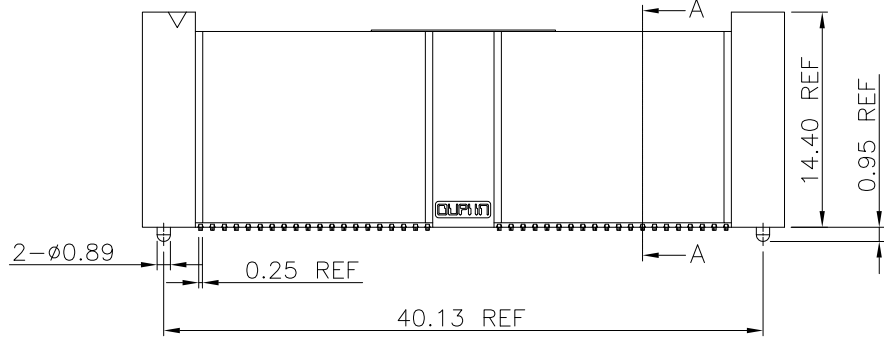
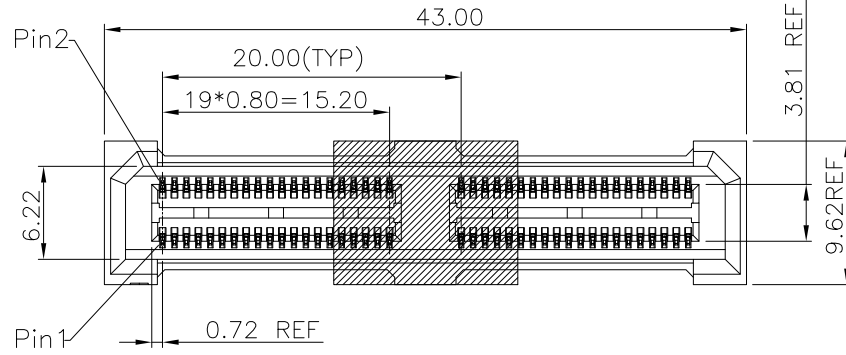
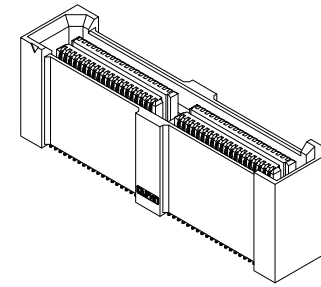
Dielectric Withstanding Voltage: 525V AC For 1 minute.

Insulator Resistance: 5000MΩ min at DC 500V.

Contact Resistance: Signal Pin: 45mΩ max .

Operating Temperature: -55°C ~ +125°C .

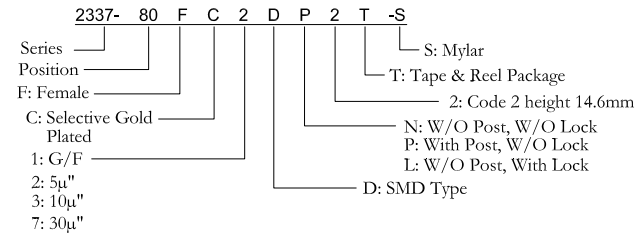
***RoHS Compliant**



Mating With Male:
2337-80MC2DP2T-S

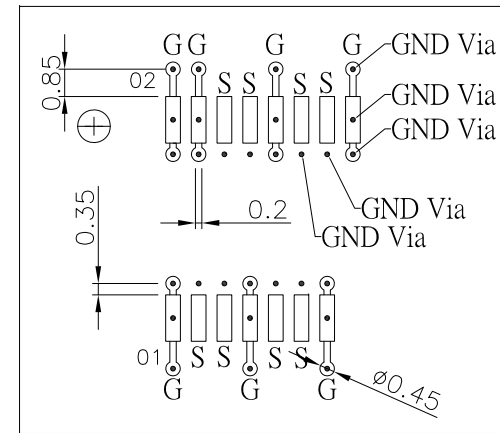
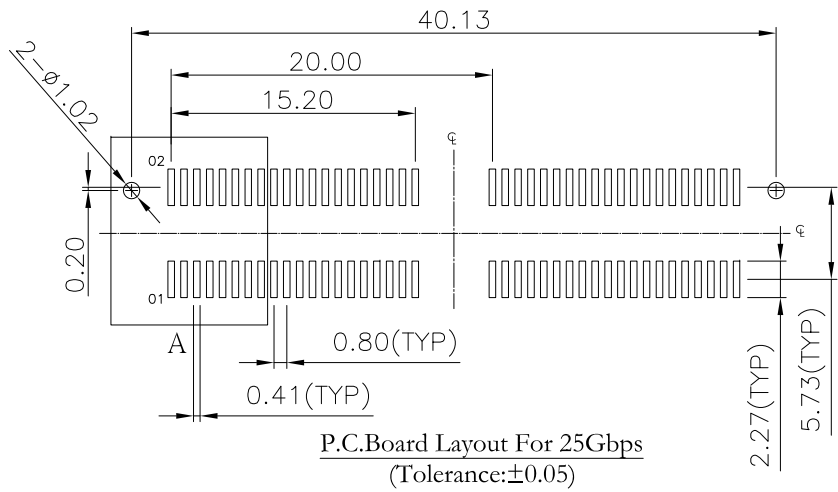
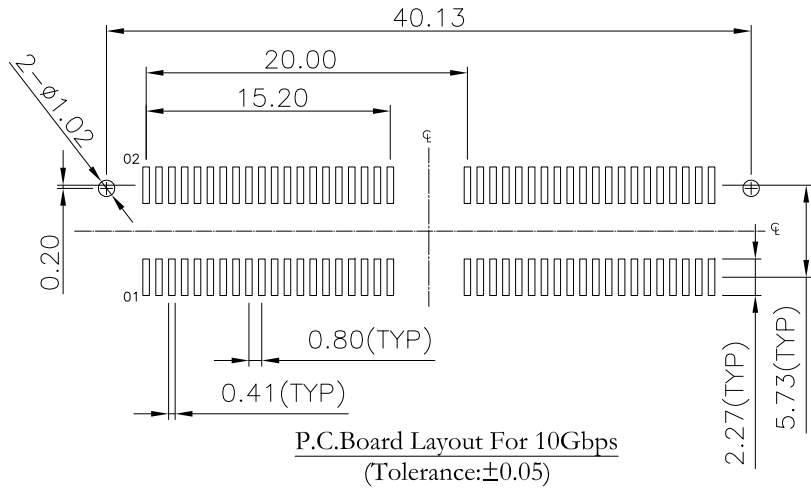
Mating With Male:
2337-Z80MC2DP1T-S

Mating Height



Tolerances	Dwg No.	2337-D0000-009	Title:		 OUPIIN ELECTRONIC(KUNSHAN) CO., LTD. P/N: 2337-80FC2DP2T-S
x. = ±0.50	Projection		2337 Series		
.x = ±0.25	Unit	mm	Scale	1:1	
.xx = ±0.15	Drawn By	WP 03/19'22	High Speed Board to Board		SHEET
			Pitch 0.8mm		1/2
					Ver.No.
					R1

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x. = ±0.50	Projection		2337 Series		
.x = ±0.25	Unit	mm	Scale	1:1	SHEET
.xx = ±0.15	Drawn By	WP 03/19'22	High Speed Board to Board		2/2
			Pitch 0.8mm		Ver.No.
					R1